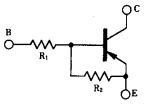


COMPOUND TRANSISTOR BN1L3N

on-chip resistor PNP silicon epitaxial transistor For mid-speed switching

FEATURES

- On-chip bias resistor (R1 = 4.7 kΩ, R2 = 10 kΩ)
- Complementary transistor with BA1L3N

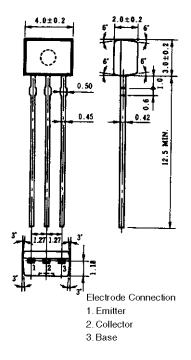


ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	Vсво	-60	V
Collector to emitter voltage	VCEO	-50	V
Emitter to base voltage	VEBO	-5	V
Collector current (DC)	IC(DC)	-100	mA
Collector current (Pulse)	IC(pulse) *	-200	mA
Total power dissipation	Ρτ	250	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

* PW \leq 10 ms, duty cycle \leq 50 %

ELECTRICAL CHARACTERISTICS (Ta = 25°C)



PACKAGE DRAWING (UNIT: mm)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -50 \text{ V}, \text{ Ie} = 0$			-100	nA
DC current gain	hfe1 **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -5.0 \text{ mA}$	35	60	100	-
DC current gain	hfe2 **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -50 \text{ mA}$	80	200		-
Collector saturation voltage	VCE(sat) **	$I_{C} = -5.0 \text{ mA}, I_{B} = -0.25 \text{ mA}$		-0.04	-0.2	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ I}_{B} = -100 \ \mu\text{A}$		-0.9	-0.6	V
High level input voltage	ViH **	$V_{CE} = -0.2 \text{ V}, \text{ Ic} = -5.0 \text{ mA}$	-3.0	-1.5		V
Input resistance	R1		3.29	4.7	6.11	kΩ
E-to-B resistance	R2		7	10	13	kΩ
Turn-on time	ton	$Vcc = -5 V, RL = 1 k\Omega$			0.2	μs
Storage time	tstg	$V_{I} = -5 V$, PW = 2 μ s			5.0	μs
Turn-off time	toff	duty cycle≤2 %			6.0	μs

** PW \leq 350 μ s, duty cycle \leq 2 %

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-8.0

V_{CE} = - 5.0 V

10

- 100

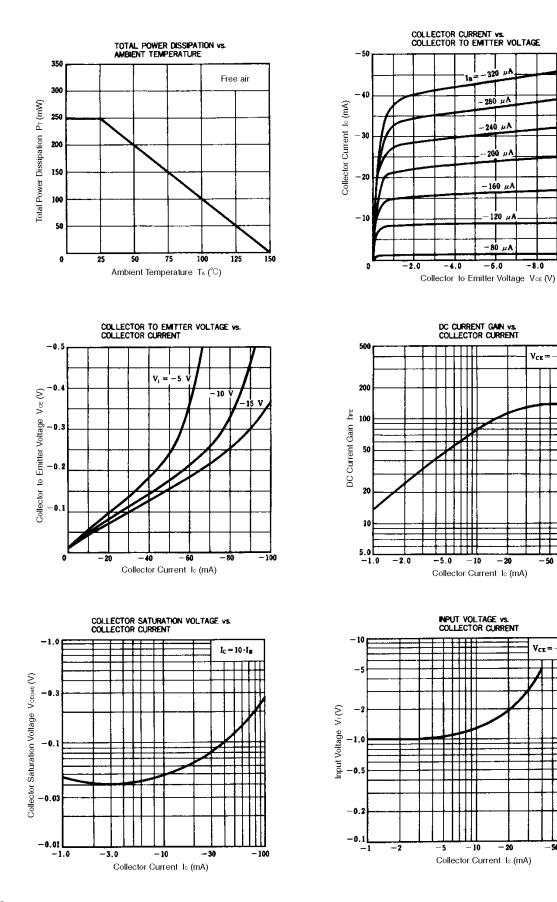
- 50

 $V_{CE} = -0.2$

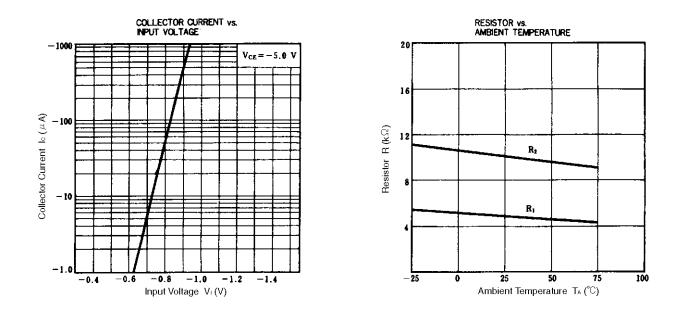
- 50

- 100

TYPICAL CHARACTERISTICS (Ta = 25°C)



Data Sheet D13588EJ1V0DS



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